ABBOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pan-An	Bannockbu	rn. Illinois. A	ll rights reserved un tions.	nder both	This docume level parts, t	ent is a declaration en	n of the substa compasses all	ances within the manufa lower level materials fo	cturer listed	d item. Note: if e manufacturer	the item is an as has engineering	ssembly with lower responsibility.	
	21.1 IPC Web Site for Information on IPC-1752 Standard Fo http://www.ipc.org/IPC-175x Di				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and				terials and	Mfg Informatio	on		
Supplier Information													
Company name* Company u			unique ID			Unique ID Authority				Response Date*			
nsemi								2024-04-25					
ontact Name Title - Contact			et	Phone			one - Contact*			Email - Contact*			
Product-Env-Stewards Product Envir			nviro Compliance			NA			Prod	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Represent			sentative			Phone - Representative*			Email	Email - Representative*			
Product-Env-Stewards Product Env			nviro Compliance		NA			Prod	Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	LM317D2	M317D2TG ANA 1.5A		.5A ADJUST OUT VREG		2024-04-25		MY1	MY1		mg	Each	
Manufacturing Proccess Information	1												
Terminal Plating / Grid Array Materia	1 Terminal Base Allo		Alloy J	J-STD-020 MSL Rating		Peak Process Body Temperature		erature Max Time at P	re Max Time at Peak Tempera		er of Reflow Cy	cles	
Matte Tin (Sn) - annealed CU Alloy		1	l		260	С	30	sec	conds 3				
Comments													
evel 1 - maximum time at peak temperature d	luring sold	lering is 10-3) seconds										
for more information regarding material com	position p	lease refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company that agreement, will be the sole and exclusive	e indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, ium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part ins a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall npass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. bany acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not endently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the ication in this paragraph. If the Company and the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the inty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.19	mg	Supplier	Silicon (Si)	7440-21-3		0.19	mg
Die Attach	11.31	mg	А	Lead (Pb)	7439-92-1	7a	10.7445	mg
			Supplier	Tin (Sn)	7440-31-5		0.5655	mg
Lead Frame 3	340.51	mg	Supplier	Iron (Fe)	7439-89-6		0.3405	mg
			Supplier	Copper (Cu)	7440-50-8		340.0674	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1022	mg
Mold Compound-Black	529.31	mg		Epoxy resin	proprietary data		15.8793	mg
				Phenolic Resin	Proprietary Data		7.9396	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		79.3965	mg
			Supplier	Carbon Black (C)	1333-86-4		2.6465	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		423.448	mg
Plating	27.15	mg	Supplier	Tin (Sn)	7440-31-5		27.15	mg
Wire Bond - Cu	0.74	mg	Supplier	Copper (Cu)	7440-50-8		0.74	mg